



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Series UP1 Series for TO-3 Outline and Stud Mount Devices

Technical Data

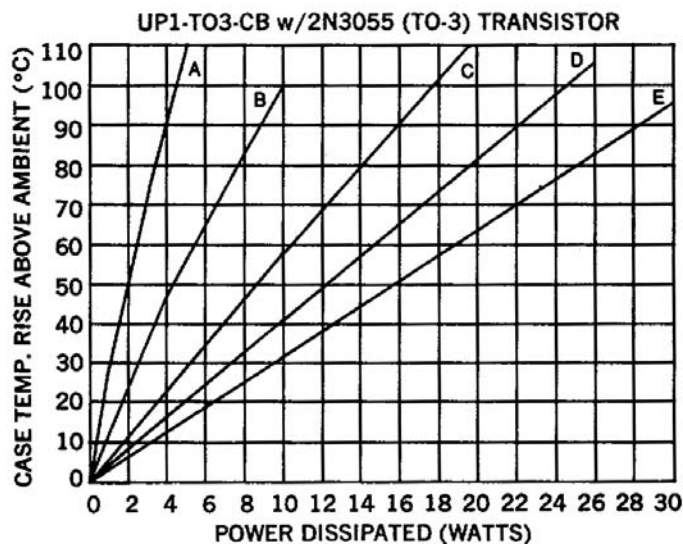
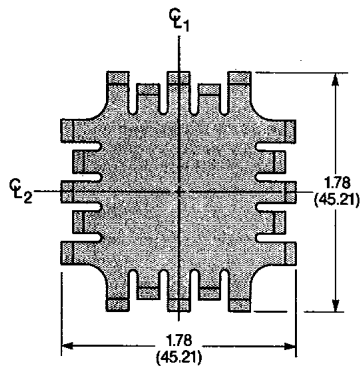
METAL CASE, CASE-MOUNTED SEMICONDUCTORS

UP1 Series for TO-3 Outline and Stud Mount Devices

Natural Conv. ($^{\circ}\text{C}/\text{W}$): 10.4

Forced Air ($^{\circ}\text{C}/\text{W}$): 3.2

Mounting Envelope: 1.78" x 1.78" x .50"



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.1-0.3 $^{\circ}\text{C}/\text{W}$ w/Joint Compound.
- Derate 0.7 $^{\circ}\text{C}/\text{watt}$ for unplated part in natural convection only.
- Derate 0.4 $^{\circ}\text{C}/\text{watt}$ for Insulube® part in natural convection only.

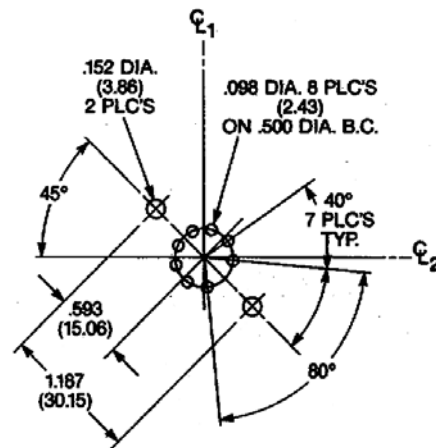
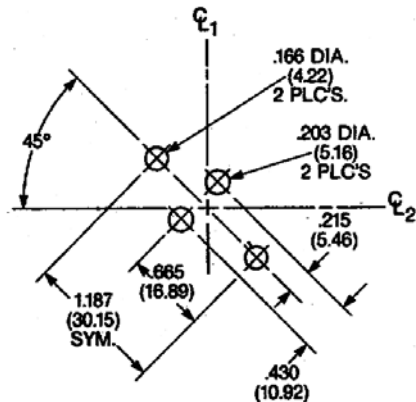
Ordering Information

CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
UP1-000-U	UP1-000-CB	UP1-000-B	Undrilled	--	15.5
UP1-T03-U	UP1-T03-CB	UP1-T03-B	T0-3	16	15.5
UP1-T03-46U	UP1-T03-46CB	UP1-T03-46B	T0-3 IC	17	15.5
UP1-436-U	UP1-436-CB	UP1-436-B	TO-3 (4-pin)	18	15.5
UP1-T06-U	UP1-T06-CB	UP1-T06-B	T0-6, T0-36	19	15.5
UP1-T015-U	UP1-T015-CB	UP1-T015-B	T0-15, D0-5	23	15.5
UP1-420-U	UP1-420-CB	UP1-420-B	Universal	27	15.5
UP1-T0V-7U	UP1-T0V-7CB	UP1-T0V-7B	Universal	28	15.5

HOLE PATTERNS

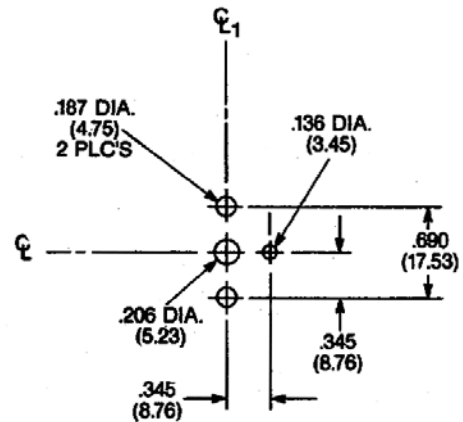
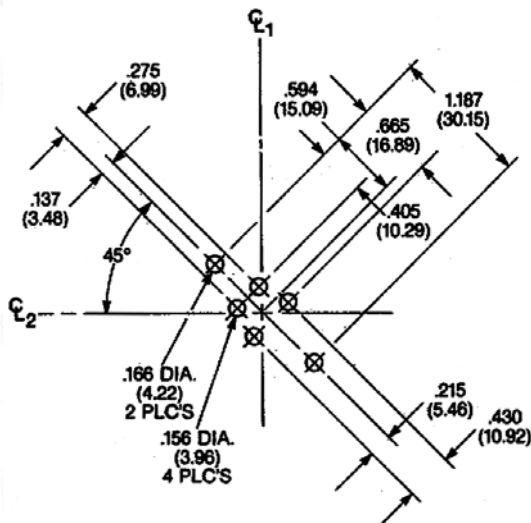
16. Hole pattern no. 1 accommodates T0-3s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.

17. Hole pattern no. 202 accommodates T0-3 ICs. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.

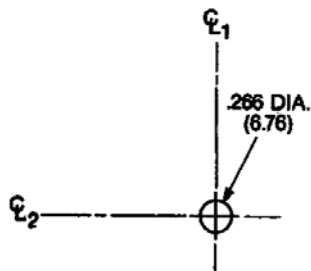


18. Hole pattern no. 436 accommodates t0-3s (4-pin). Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.

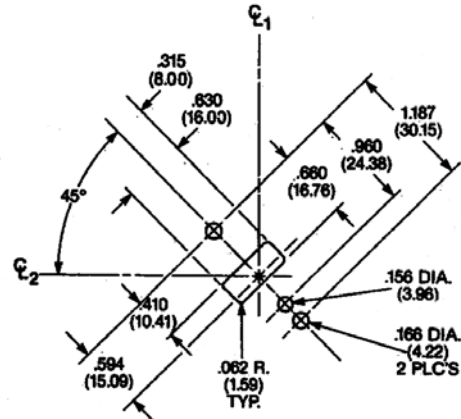
19. Hole pattern no. 2 accommodates T0-6s or T0-36s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



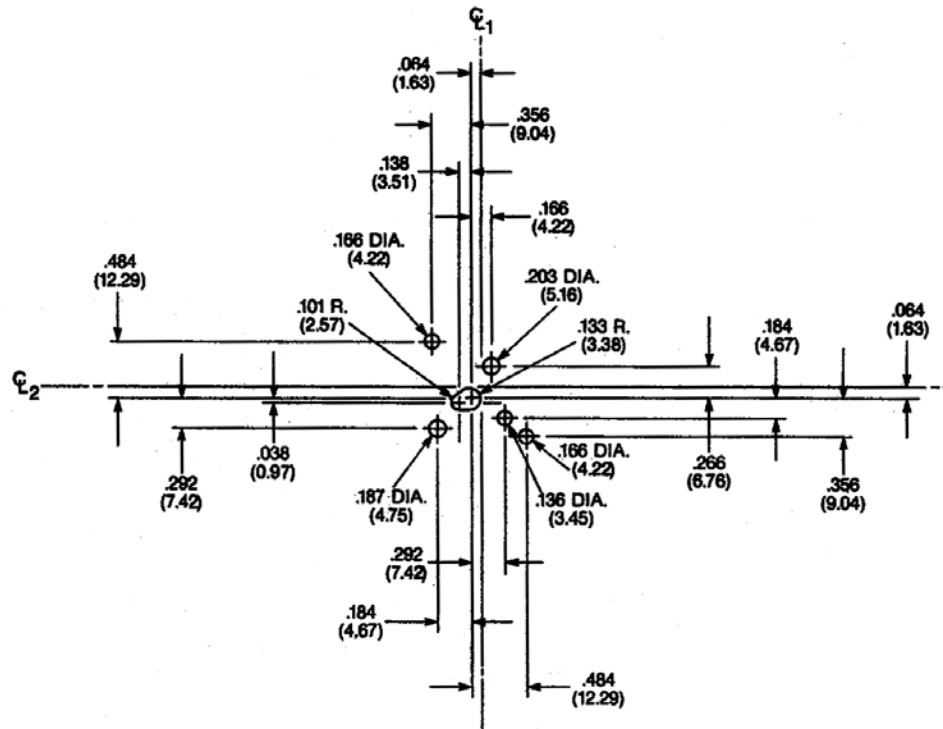
23. Hole pattern no. 3 accommodates T0-15s, D0-5s and other 1/4" stud mount devices. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



27. Hole pattern no. 420 (Universal) accommodates T0-3s, T0-66s, T0-126s, T0-127s, or T0-220s. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



28. Hole pattern no. 64 (Universal) accommodates T0-3s, D0-4s, T0-15s, T0-6s, T0-36s, or other stud mounted devices up to 1/4" diameter. Available in UP, UP1, UP2, HP1, and HP3 series heat dissipators.



CTS IERC, Heat Sinks and Thermal Management Solutions

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